

PCN# : P34KA
Issue Date : May. 10, 2013

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the following products.

This is a minor change that has no impact on product quality, reliability, electrical or mechanical performance. Affected products will remain fully compliant to all published specifications. Notification is being made for informational purposes only and there is no approval required. Products incorporating this change may be shipped interchangeably with existing unchanged products.

Please contact your local Customer Quality Engineer if you have any questions regarding this notification. Alternatively, you may send an email request for information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jul. 01, 2013

Expected First Date Code of Changed Product :1319

Description of Change (From) :

Wafer backmetal stack of Al/Ti/NiV/Ag with corresponding thickness of (5KA/3KA/3.5KA/18.5KA)

Description of Change (To) :

Wafer backmetal stack of Al/Ti/NiV/Ag with corresponding thickness of (5KA/3KA/2KA/10KA)

Reason for Change:

The reason for this change is to standardize on the wafer back metal thickness for this particular die technology.

Affected Product(s):

FGD3040G2_F085	FGD3440G2_F085	
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